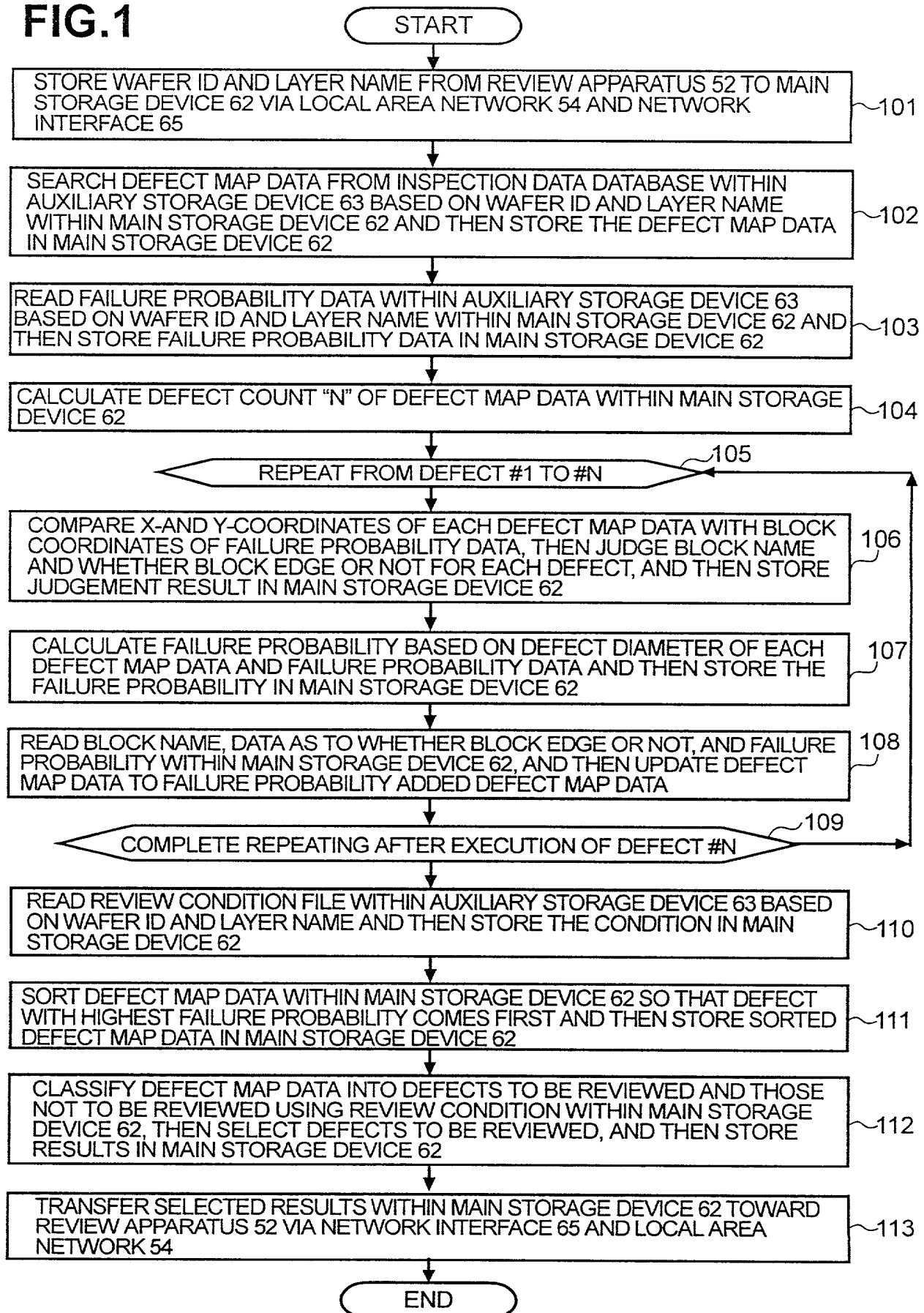


FIG.1



Applicant: Makoto Ono, et al.

Title: Inspection System and Semiconductor Device Manufacturing...

Atty Docket No. 16869P-037300

Sheet 2 of 12

FIG.2

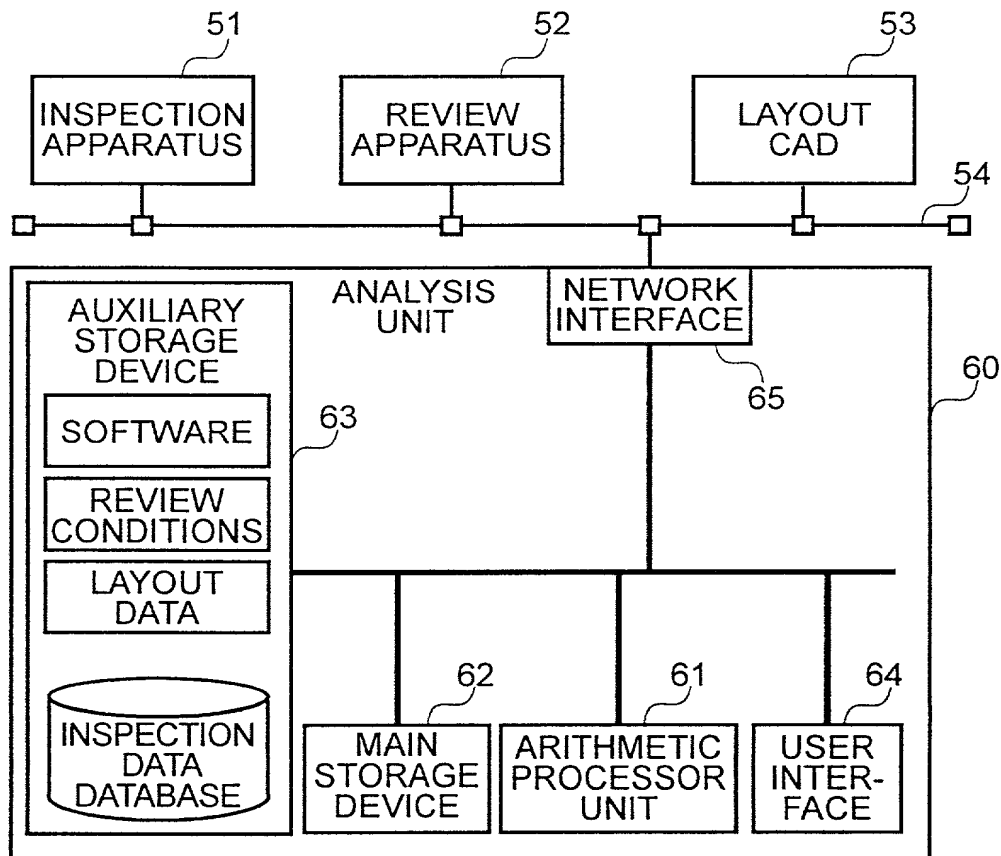


FIG.3

CHIP NO.,	CHIP COLUMN,	CHIP ROW,	X,	Y,	DEFECT DIAMETER
1,	1,	1,	73,	67,	2.4
2,	5,	1,	25,	89,	0.3
3,	4,	2,	47,	69,	1.5
4,	5,	3,	80,	82,	1.0
5,	6,	5,	52,	78,	1.2
6,	3,	5,	71,	32,	0.2
7,	3,	7,	87,	90,	0.7
8,	2,	6,	77,	38,	0.3
9,	0,	4,	83,	45,	0.8
10,	2,	3,	49,	9,	1.9

FIG.4

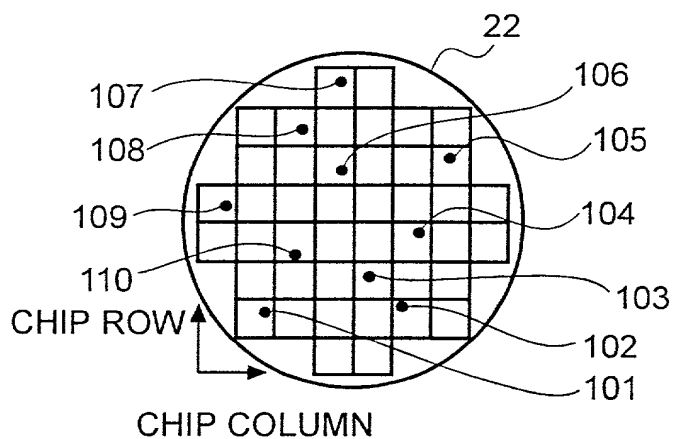


FIG.5

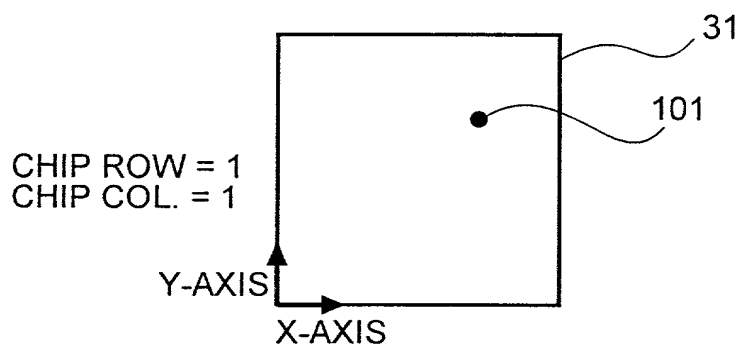


FIG.6

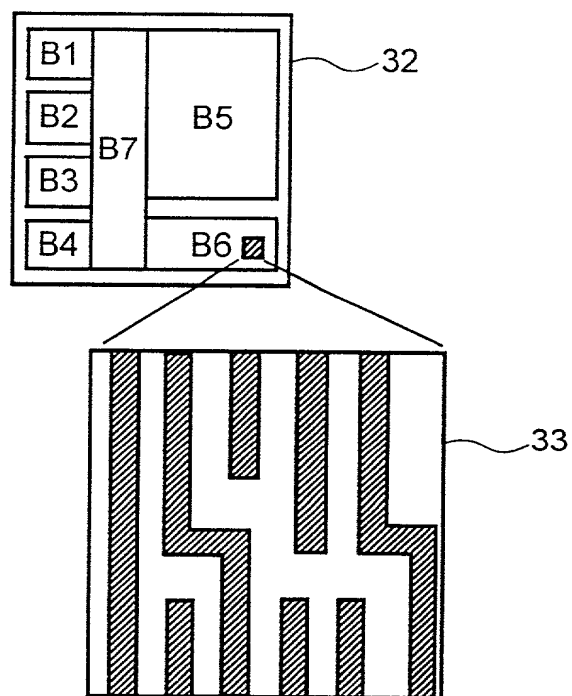


FIG.7

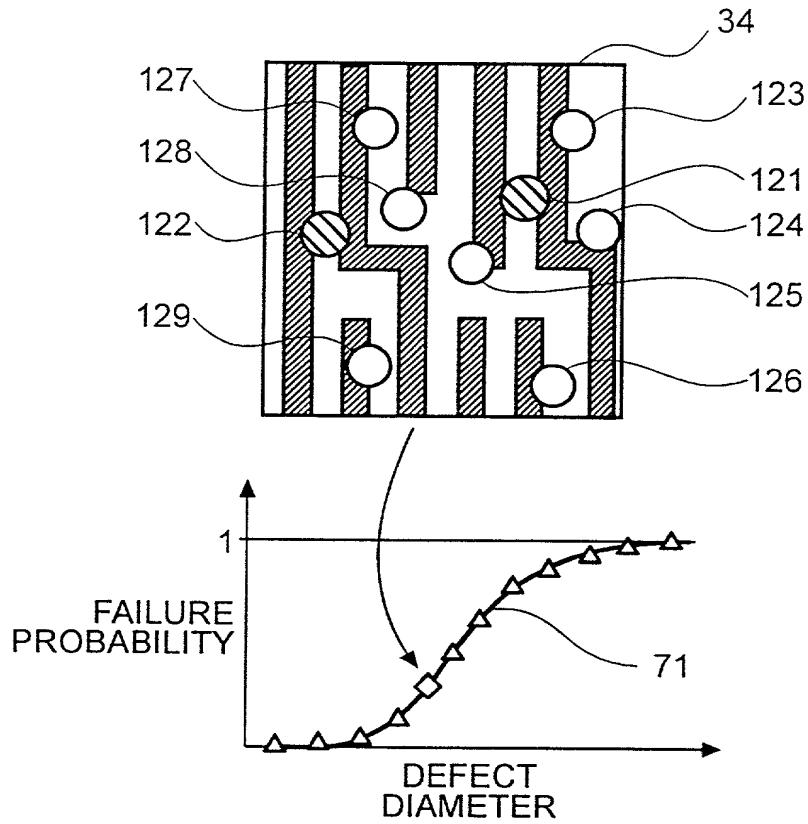


FIG.8

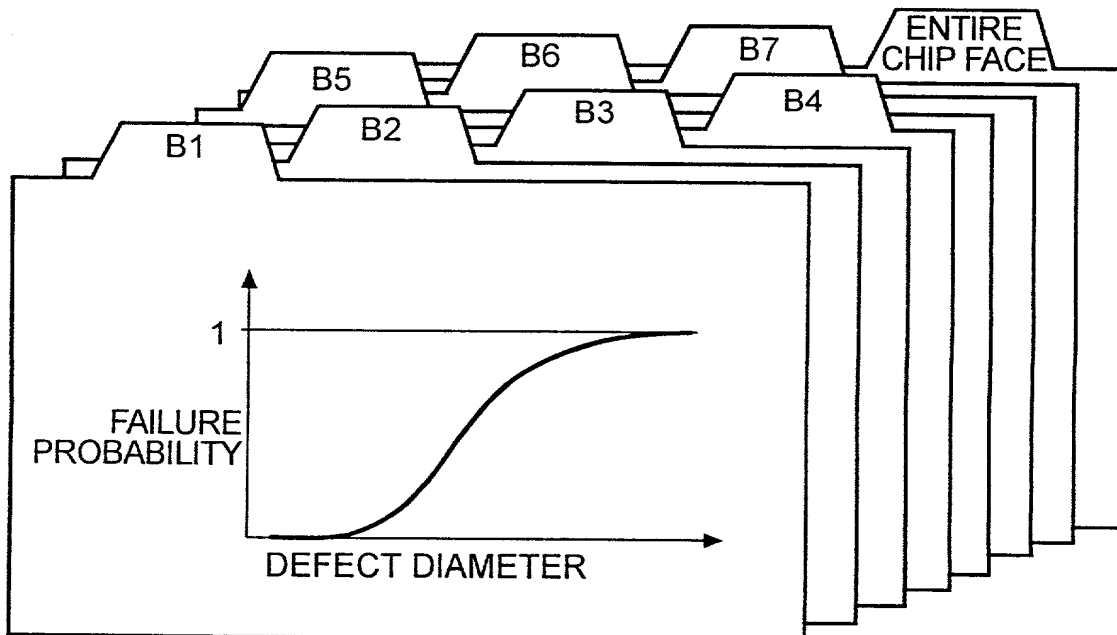
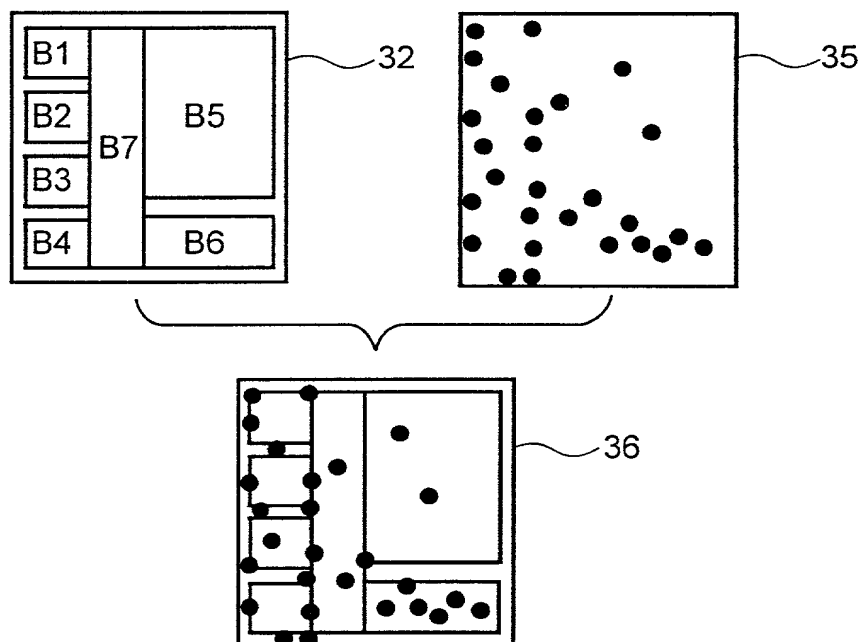


FIG.9

PRODUCT TYPE NAME	
LOGIC234	
LAYER NAME	
METAL1	
BLOCK NAME	
B1	
BLOCK COORDINATES	
RECTANGLE DIAGONAL	
ANGLE (5, 80) - (20, 95)	
DEFECT	FAILURE
DIAMETER	PROBABILITY
0.05,	0.00
0.10,	0.01
0.15,	0.02
0.20,	0.03
0.25,	0.05
.	.
.	.
9.95,	1.00
10.00,	1.00

FIG.10



Applicant: Makoto Ono, et al.

Title: Inspection System and Semiconductor Device Manufacturing...

Atty Docket No. 16869P-037300

Sheet 7 of 12

FIG.11

23

NO.,	CHIP COL.,	CHIP ROW,	X,	Y,	SIZE,	BLOCK,	BLOCK EDGE,	FAILURE PROBABILITY
1,	1,	1,	73,	67,	2.4,	B5,	no,	0.83
2,	5,	1,	25,	89,	0.3,	B1,	no,	0.07
3,	4,	2,	47,	69,	1.5,	B2,	no,	0.26
4,	5,	3,	80,	82,	1.0,	B5,	no,	0.38
5,	6,	5,	52,	78,	1.2,	B5,	yes,	0.50
6,	3,	5,	71,	32,	0.2,	B6,	yes,	0.05
7,	3,	7,	87,	90,	0.7,	B5,	no,	0.35
8,	2,	6,	77,	38,	0.3,	B6,	no,	0.07
9,	0,	4,	83,	45,	0.8,	B5,	no,	0.28
10,	2,	3,	49,	9,	1.9,	B7,	no,	0.06

FIG.12

24

NO.,	CHIP COL.,	CHIP ROW,	X,	Y,	SIZE,	BLOCK,	BLOCK EDGE,	FAILURE PROBABILITY
1,	1,	1,	73,	67,	2.4,	B5,	no,	0.83
5,	6,	5,	52,	78,	1.2,	B5,	yes,	0.50
4,	5,	3,	80,	82,	1.0,	B5,	no,	0.38
7,	3,	7,	87,	90,	0.7,	B5,	no,	0.35
9,	0,	4,	83,	45,	0.8,	B5,	no,	0.28
3,	4,	2,	47,	69,	1.5,	B2,	no,	0.26
8,	2,	6,	77,	38,	0.3,	B6,	no,	0.07
2,	5,	1,	25,	89,	0.3,	B1,	no,	0.07
10,	2,	3,	49,	9,	1.9,	B7,	no,	0.06
6,	3,	5,	71,	32,	0.2,	B6,	yes,	0.05

Applicant: Makoto Ono, et al.

Title: Inspection System and Semiconductor Device Manufacturing...

Atty Docket No. 16869P-037300

Sheet 8 of 12

FIG.13

26

NO.,	CHIP COL.,	CHIP ROW,	X,	Y,	SIZE,	BLOCK,	BLOCK EDGE,	FAILURE PROBABILITY
1,	1,	1,	73,	67,	2.4,	B5,	no,	0.83
4,	5,	3,	80,	82,	1.0,	B5,	no,	0.38
7,	3,	7,	87,	90,	0.7,	B5,	no,	0.35
9,	0,	4,	83,	45,	0.8,	B5,	no,	0.28
3,	4,	2,	47,	69,	1.5,	B2,	no,	0.26

FIG.14

27

NO.,	CHIP COL.,	CHIP ROW,	X,	Y,	SIZE,	BLOCK,	BLOCK EDGE,	FAILURE PROBABILITY
3,	4,	2,	47,	69,	1.5,	B2,	no,	0.26
8,	2,	6,	77,	38,	0.3,	B6,	no,	0.07
2,	5,	1,	25,	89,	0.3,	B1,	no,	0.07
10,	2,	3,	49,	9,	1.9,	B7,	no,	0.06
6,	3,	5,	71,	32,	0.2,	B6,	yes,	0.05



Applicant: Makoto Ono, et al.

Title: Inspection System and Semiconductor Device Manufacturing...

Atty Docket No. 16869P-037300

Sheet 9 of 12

FIG.15

25

NO.,	CHIP COL.,	CHIP ROW,	X,	Y,	SIZE,	BLOCK,	BLOCK EDGE,	FAILURE PROBABILITY
1,	1,	1,	73,	67,	2.4,	B5,	no,	0.83
5,	6,	5,	52,	78,	1.2,	B5,	yes,	0.50
4,	5,	3,	80,	82,	1.0,	B5,	no,	0.38
7,	3,	7,	87,	90,	0.7,	B5,	no,	0.35
9,	0,	4,	83,	45,	0.8,	B5,	no,	0.28

FIG.16

41

PRODUCT TYPE NAME  
LOGIC234  
LAYER NAME  
METAL1  
MAXIMUM DEFECT NUMBER  
20  
OBJECT  
FAILURE PROBABILITY  
0.30 OR GREATER  
EXCLUDED  
B5  
BLOCK EDGES B1, B2

FIG.17

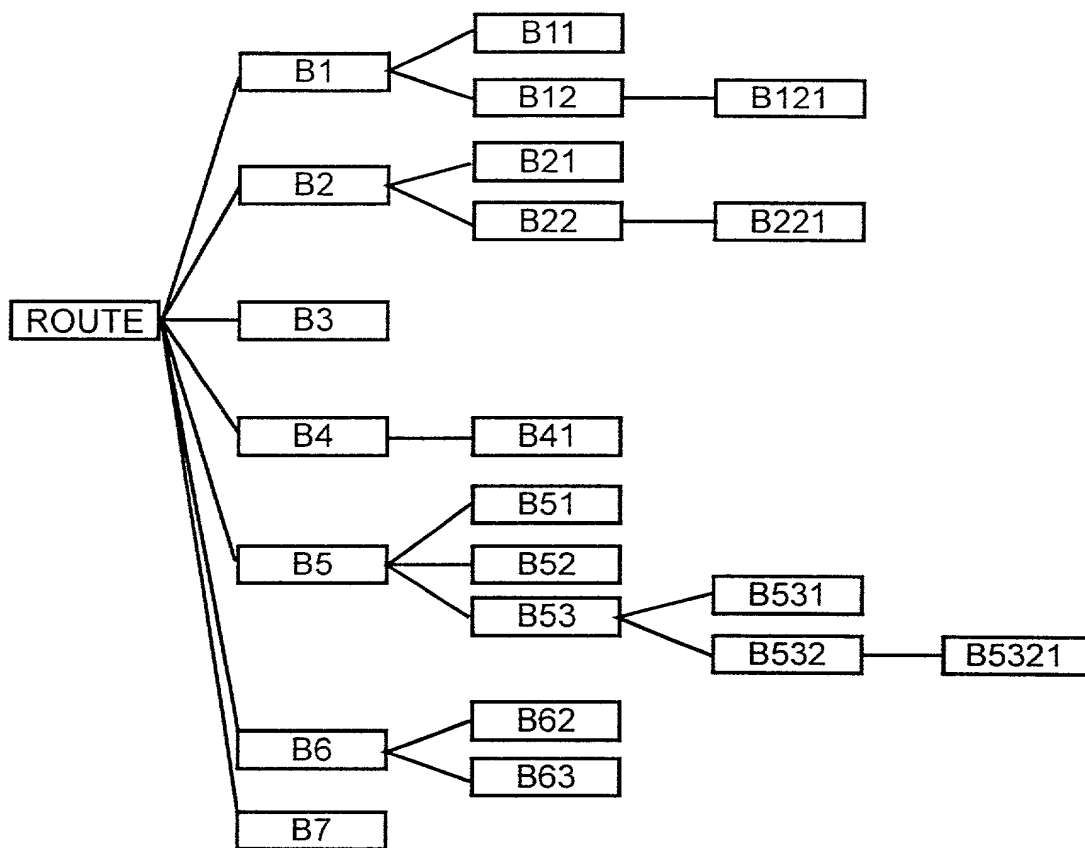
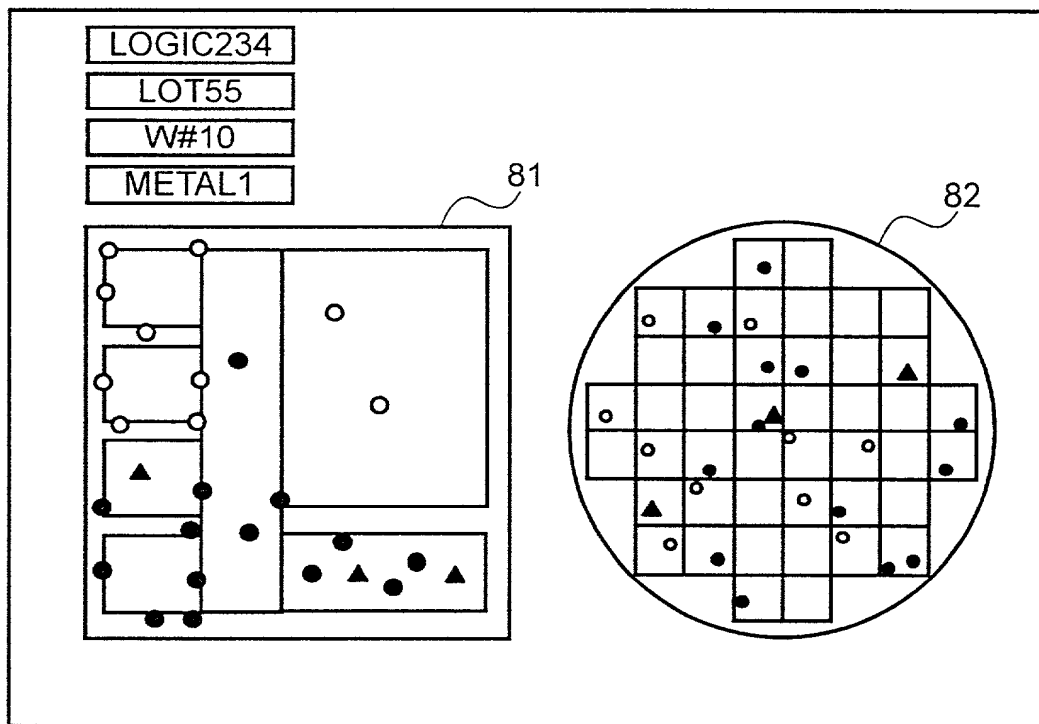


FIG.18



Applicant: Makoto Ono, et al.

Title: Inspection System and Semiconductor Device Manufacturing...

Atty Docket No. 16869P-037300

Sheet 12 of 12

FIG.19

